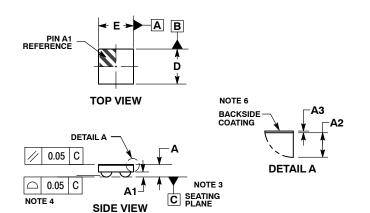
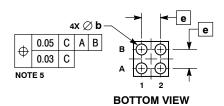


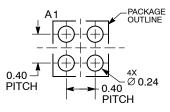
WLCSP4, 0.77x0.77x0.3 CASE 567PN ISSUE O

**DATE 11 AUG 2016** 





## **RECOMMENDED SOLDERING FOOTPRINT\***



**DIMENSIONS: MILLIMETERS** 

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- CONTROLLING DIMENSION: MILLIMETERS.
  DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- COPLANARITY APPLIES TO SPHERICAL CROWNS OF THE SOLDER BALLS.
- DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C. 6. BACKSIDE COATING IS OPTIONAL.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α			0.30	
A1	0.09	0.11	0.13	
A2	0.14 REF			
A3	0.025 REF			
b	0.22	0.24	0.26	
D	0.75	0.77	0.79	
E	0.75	0.77	0.79	
е	0.40 BSC			

## **GENERIC MARKING DIAGRAM\***



= Specific Device Code

= Year

W = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator. "G" or microdot " ■". may or may not be present.

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DESCRIPTION:	WLCSP4, 0.77X0.77X0.3		PAGE 1 OF 1

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